L Number	Hits	Search Text	DB	Time stamp
1	3111	257/762.ccls. 257/767.ccls. 257/768.ccls. 257/751.ccls. 438/627.ccls. 438/643.ccls. 438/653.ccls.	USPAT; US-PGPUB	2003/07/23 09:48
2	1095	(257/762.ccls. 257/767.ccls. 257/768.ccls. 257/751.ccls. 438/627.ccls. 438/643.ccls. 438/653.ccls.) and (copper cu platinum pt) and (platinum pt osmium os ruthenium ru iridium ir rhodium rh)	USPAT; US-PGPUB	2003/07/23 09:50
3	751	(257/762.ccls. 257/767.ccls. 257/768.ccls. 257/751.ccls. 438/627.ccls. 438/643.ccls. 438/653.ccls.) and ((copper cu platinum pt) with (platinum pt osmium os ruthenium ru iridium ir rhodium rh))	USPAT; US-PGPUB	2003/07/23 09:54
4	409	((257/762.ccls. 257/767.ccls. 257/768.ccls. 257/751.ccls. 438/627.ccls. 438/643.ccls. 438/653.ccls.) and (copper cu platinum pt) and (platinum pt osmium os ruthenium ru iridium ir rhodium rh)) and (electromigrat$5 void)	USPAT; US-PGPUB	2003/07/23 09:52
5	402	(((257/762.ccls. 257/767.ccls. 257/768.ccls. 257/751.ccls. 438/627.ccls. 438/643.ccls. 438/653.ccls.) and (copper cu platinum pt) and (platinum pt osmium os ruthenium ru iridium ir rhodium rh)) and (electromigrat$5 void)) and (interconnect$6 diffusion barrier)	USPAT; US-PGPUB	2003/07/23 09:52
7	1466	((((CU OR COPPER) WITH INTERCON$10)) AND (DIFFUSION ADJ BARRIER))	USPAT; US-PGPUB	2003/07/23 09:56
8	392	(257/762.ccls. 257/767.ccls. 257/768.ccls. 257/751.ccls. 438/627.ccls. 438/643.ccls. 438/653.ccls.) and (((((CU OR COPPER) WITH INTERCON$10)) AND (DIFFUSION ADJ BARRIER)))	USPAT; US-PGPUB	2003/07/23 09:56
9	49	(((pt OR platinum) WITH INTERCON$10)) same (diffusion adj barrier)	USPAT; US-PGPUB	2003/07/23 09:57
10	234	((RU OR RUTHENIUM or pt or ir or os or rh or iridium or platinum or osmium or rhodium) same electromigration)	USPAT; US-PGPUB	2003/07/23 09:57
11	179	(((RU OR RUTHENIUM or pt or ir or os or rh or iridium or platinum or osmium or rhodium) and electromigration)) and (copper or cu)	EPO; JPO; DERWENT; IBM_TDB	2003/07/23 09:57
12	216	((RU OR RUTHENIUM) and (DIFFUSION ADJ BARRIER))	EPO; JPO; DERWENT; IBM_TDB	2003/07/23 09:58
13	30	((RUTHENIUM or iridium or platinum or osmium or rhodium) and electromigration)	EPO; JPO; DERWENT; IBM_TDB	2003/07/23 09:58
6	46	(257/762.ccls. 257/767.ccls. 257/768.ccls. 257/751.ccls. 438/627.ccls. 438/643.ccls. 438/653.ccls.) and ((copper cu platinum pt) same (interconnect$6 diffusion barrier) same (platinum pt osmium os ruthenium ru iridium ir rhodium rh) same (electromigrat$5 void))	USPAT; US-PGPUB	2003/07/23 09:58